SDLS205 - DECEMBER 1983 - REVISED MARCH 1988

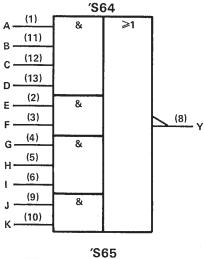
- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

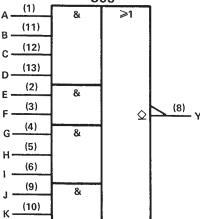
description

These devices contain 4-2-3-2 input AND-OR-INVERT gates. They perform the Boolean function $Y = \overline{ABCD + EF + GHI + JK}$. The 'S64 has totem-pole outputs and the 'S65 has open-collector outputs.

The SN54S64 and the SN54S65 are characterized for operation over the full military temperature range of $-55\,^{\circ}\text{C}$ to 125 $^{\circ}\text{C}$. The SN74S64 and the SN74S65 are characterized for operation from 0 $^{\circ}\text{C}$ to 70 $^{\circ}\text{C}$.

logic symbols†

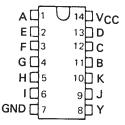




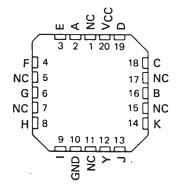
[†]These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

SN54S64, SN54S65 . . . J OR W PACKAGE SN74S64, SN74S65 . . . D OR N PACKAGE (TOP VIEW)

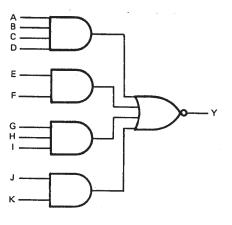


SN54S64, SN54S65 . . . FK PACKAGE (TOP VIEW)



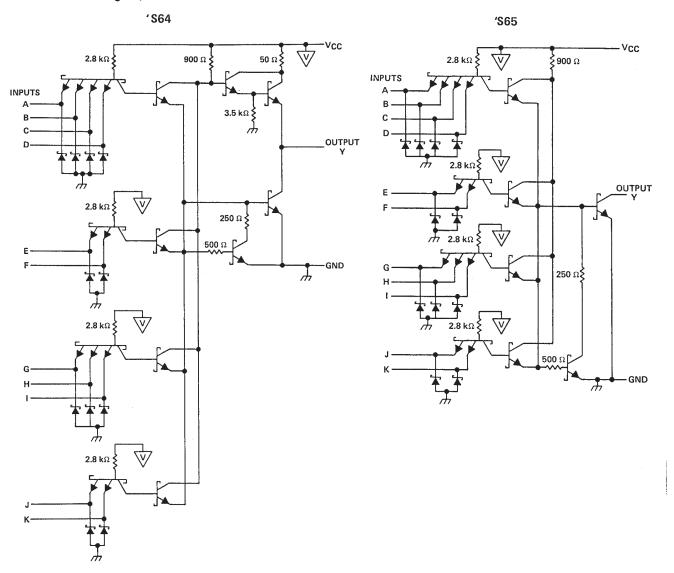
NC - No internal connection

logic diagram (each device) (positive logic)



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schematics (each gate)



Resistor values shown are nominal and in ohms.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)		7 V
Input voltage		5.5 V
Off-state output voltage, 'S65		7 V
Operating free-air temperature range:	SN54'	
	SN74'	0°C to 70°C
Storage temperature range		- 65°C to 150°C



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recommended operating conditions

	S	SN54S64			SN74S64			
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
V _{CC} Supply voltage	4.5	5	5,5	4.75	5	5.25	V	
V _{IH} High-level input voltage	2			2			V	
VIL Low-level input voltage			8,0			0,8	V	
IOH High-level output current			<u> </u>			-1	mA	
IOL Low-level output current			20			20	mA	
T _A Operating free-air temperature	– 55		125	0		70	°c	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDIT								
		TEGT CONDIT	TONS I.	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT
VIK	V _{CC} = MIN,	$I_{1} = -18 \text{ mA}$				-1,2			- 1.2	V
v _{oh}	V _{CC} = MIN,	V _{1L} = 0.8 V,	I _{OH} = -1 mA	2.5	3.4		2.7	3.4		V
VOL	V _{CC} = MIN,	V _{IH} = 2 V,	1 _{OL} = 20 mA			0,5			0.5	V
կ	$V_{CC} = MAX$,	V ₁ = 5.5 V				1			1	mA
ЧН	V _{CC} = MAX,	V ₁ = 2.7 V				50			50	μΑ
HL	V _{CC} = MAX,	V ₁ = 0.5 V				- 2			- 2	mA
loss	V _{CC} = MAX			- 40		-100	- 40		- 100	mA
Іссн	V _{CC} = MAX,	V1 = 0			7	12.5		7	12,5	mA
ICCL	V _{CC} = MAX,	V ₁ = 4.5 V			8.5	16		8.5	16	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CON	MIN TY	P MAX	UNIT	
t _{PLH}			B. = 300 C	0 -15-5	3.	5 5.5	ns
^t PHL	Any		$R_L = 280 \Omega$,	$C_L = 15 pF$	3.	5 5.5	ns
tPLH	Ally	'	D. = 200 C	0 50 . 5		5	ns
^t PHL			$R_L = 280 \Omega$,	$C_L = 50 pF$	5.	5	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ} \text{C}$. § Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

recommended operating conditions

		SN54S65			SN74S65			
	MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
V _{CC} Supply voltage	4.5	5	5.5	4.75	5	5.25	V	
V _{1H} High-level input voltage	2			2			V	
V _{IL} Low-level input voltage			8.0			8.0	V	
VOH High-level output voltage			5.5			5.5	V	
OL Low-level output current			20			20	mA	
T _A Operating free-air temperature	– 55		125	0	·	70	°c	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS†	<u> </u>	SN54S6	5		LIBUT		
	TEST CONDITIONS.	MIN	TYP [‡]	MAX	MIN	TYP [‡]	MAX	UNIT
V _{IK}	$V_{CC} = MIN$, $I_{\parallel} = -18 \text{ mA}$			1.2			1.2	V
ЮН	$V_{CC} = MIN$, $V_{IL} = 0.8 \text{ V}$, $V_{OH} = 5.5 \text{ V}$						0.25	
'ОП	$V_{CC} = MIN$, $V_{IL} = 0.7 \text{ V}$, $V_{OH} = 5.5 \text{ V}$			0.25				mA
V _{OL}	$V_{CC} = MIN$, $V_{IH} = 2 V$, $I_{OL} = 20 mA$		0.2	0.4		0.2	0.4	V
I _I	$V_{CC} = MAX$, $V_1 = 5.5 V$			1			1	mA
liH .	$V_{CC} = MAX$, $V_{I} = 2.7 V$			50			50	μΑ
Iլլ	$V_{CC} = MAX$, $V_1 = 0.5 V$			-2			- 2	mA
Іссн	$V_{CC} = MAX, V_I = 0$		6	11		6	11	mA
^I CCL	$V_{CC} = MAX$, $V_1 = 4.5 V$		8.5	16		8.5	16	mA

[†]For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions. ‡ All typical values are at V_{CC} = 5 V, T_A = 25 °C.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CON	DITIONS	MIN	TYP	MAX	UNIT
t _{PLH}			$R_1 = 280 \Omega$,	C 15 - F	2	5	7.5	ns
t _{PHL}	Any	v L	n 200 12,	C _L = 15 pF	2	5.5	8.5	ns
^t PLH	,,	'	$R_1 = 280 \Omega_s$	0. = 50 = 5		8		ns
tPHL_			n[- 200 12,	C _L = 50 pF		6.5		ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
JM38510/07402BCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	(6) SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07402BCA	Samples
JM38510/07402BDA	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07402BDA	Samples
M38510/07402BCA	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07402BCA	Samples
M38510/07402BDA	ACTIVE	CFP	W	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510/ 07402BDA	Samples
SN54S64J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SN54S64J	Samples
SNJ54S64J	ACTIVE	CDIP	J	14	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SNJ54S64J	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.



PACKAGE OPTION ADDENDUM

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(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
JM38510/07402BDA	W	CFP	14	1	506.98	26.16	6220	NA
M38510/07402BDA	W	CFP	14	1	506.98	26.16	6220	NA

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14



CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.

4040083-5/G





CERAMIC DUAL IN LINE PACKAGE



NOTES:

- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- His package is remitted by sealed with a certain is using glass int.
 Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
 Falls within MIL-STD-1835 and GDIP1-T14.



CERAMIC DUAL IN LINE PACKAGE



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